

## CLAIMS

What is claimed is:

1. An electronic device package comprising:  
a transparent substrate;  
a secondary substrate having a first surface secured to a surface of the transparent substrate, having a central aperture covered by the transparent substrate and a plurality of conductive traces formed around the central aperture, each conductive trace of the plurality of conductive traces having a first attachment point and a second attachment point on a second surface of the secondary substrate;  
an optically interactive electronic device having at least one bond pad, the optically interactive electronic device mounted to the secondary substrate by a bond between the first attachment point of a conductive trace of the plurality of conductive traces and the at least one bond pad; and  
a discrete conductive element attached to the second attachment point of the conductive trace, the discrete conductive element extending outwardly from the secondary substrate within an outside perimeter thereof from the second attachment point in a direction perpendicular to a plane of the secondary substrate and to a level beyond a back surface of the optically interactive electronic device.
2. The electronic device package according to claim 1, wherein the second attachment points of the plurality of conductive traces are located in at least one row extending adjacent a perimeter portion of the second surface of the secondary substrate.
3. The electronic device package according to claim 2, wherein the second attachment points of the plurality of conductive traces are located in multiple rows extending adjacent the perimeter portion of the second surface of the secondary substrate.
4. The electronic device package according to claim 1, wherein the secondary substrate comprises one of a printed circuit board, a polyimide film, a ceramic and silicon.

5. The electronic device package according to claim 1, wherein the outside perimeter of the secondary substrate is substantially equal to an outside perimeter of the transparent substrate.
6. The electronic device package according to claim 1, further comprising:  
a bead of sealant material contacting at least one side of the optically interactive electronic device and the second surface of the secondary substrate.
7. The electronic device package according to claim 6, wherein the bead of sealant material comprises one of epoxy and silicone.
8. The electronic device package according to claim 1, wherein the at least one discrete conductive element comprises one of a solder ball, a solder column, a conductive epoxy, and a conductor-filled epoxy.
9. The electronic device package according to claim 1, wherein the optically interactive electronic device comprises an image sensor.
10. The electronic device package according to claim 1, wherein the transparent substrate comprises a single substrate having multiple optically interactive electronic devices mounted thereto.